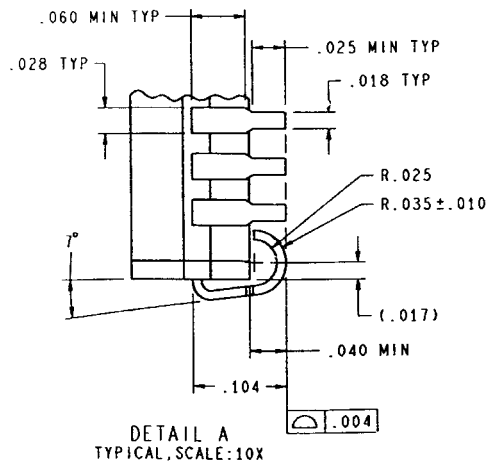
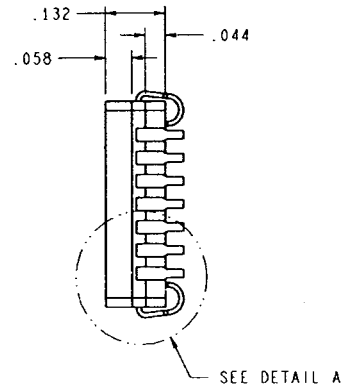
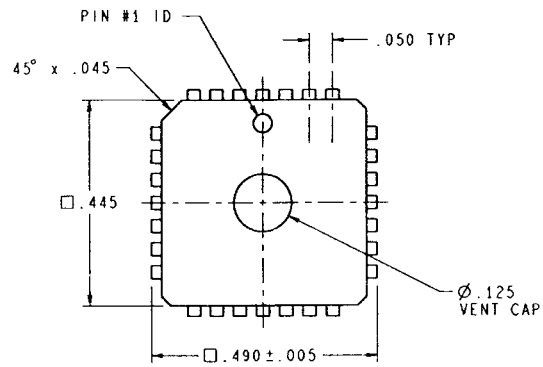


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10666	11/11/94	KES/HJC



DIMENSIONS ARE IN INCHES

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
200 MICROINCHES MINIMUM SOLDER PLATING (85/15)
THICKNESS ON ALLOY 42/COPPER.
- TOLERANCE OF LEAD FRAME TO PACKAGE BODY IS
±.020 MAXIMUM.
- REFERENCE INDY DRAWING 04-028-YO-001 REV C,
DATED 09/09/92.

APPROVALS	DATE	National Semiconductor			
DRWNG KURT SINCERBOY	11/11/94	2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DATE, CHG. 11/11/94	11/11/94	METAL LEADED CHIP CARRIER, J-BEND, .050 LD PITCH, 28 LD, CAVITY UP			
ENGR, CHG. HJ Kim	11/4/94				
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
1 INCH = 100X		N/A	C	MKT-AA28A	A
DO NOT SCALE DRAWING					SHEET 1 of 1